

# *Sensors and Materials*

## **Special Issue on Materials, Devices, Circuits, and Systems for Biomedical Sensing and Interfacing**

### **Call for Papers**

With the development of highly advanced ICT technologies supported by a high-speed and ubiquitous networking infrastructure, the demand for personalized health monitoring technology is increasing. ICT platforms and AI technologies such as machine learning are capable of handling huge amounts of data, and various kinds of vital information can be included and used as a part of big data. To meet the increasing demand for personalized health monitoring, considerable effort has been made to create new materials, devices, circuits, and systems to realize new biosensing and bio-interfacing technologies. In this special issue, we will be publishing research papers on a wide variety of biosensing and interfacing technologies, as well as their materials, devices, circuits, and systems. Various works with potential applications in both bioscientific and medical areas are welcomed.

#### **Scope:**

- Biosensing and mediator materials
- Biocompatible materials, structures, and devices
- Biomedical sensing and interfacing systems
- Electrical and optical sensing circuits
- Stimulator devices

**Submission due date:** September 30, 2021

**Publication date (planned):** First half of 2022

**Journal website:** <https://myukk.org/>

**Guest Editor:** Prof. Takashi Tokuda (Tokyo Institute of Technology)

**Submit to:** Online Manuscript Submission System (<https://myukk-org.ssl-xserver.jp/form/>)

#### **(Attention)**

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors should bear the proofreading fee (JPY 10000–30000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

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